Notific		ation Number: 20220623001.0 Notific				<b>Notification D</b>	ication Date: July 05, 2022		
Tit	le:	Datasheet for	TMAG511x						
Customer Contact: PCN Manager								pt:	Quality Services
Ch		Туре:							
	Assembly Site			Design			Wafer Bump Site		
Assembly Process			Data Sheet			Wafer Bump Material			
$\square$	Assembly Materials				Part number change			Wafer Bump Process	
			Test Site				Wafer Fab Site Wafer Fab Materials		
Packing/Shipping/Labeling			Test Proce	Test Process		Wafer Fab Process			
				N	otificatio				
Notification Details Description of Change:									
				nnc	uncing an i	nformation only	notif	icatio	p
	e follo	luct datasheet(s wing change his							
	Ť	NSTRUMENTS				:			5110-Q1, TMAG5111-Q1 Y 2021 – REVISED JUNE 2022
~		o from Dovision A	(Contombor	202		B ( June 2022)			Daga
<u>-</u>		s from Revision A				т В (June 2022)			Page 33
-	Ghai	iyeu Layout Examp							
The datasheet number will be changing.									
D	Device Family			Change From:			Change To:		
TMAG511x-Q1				SLY	SLYS029A		SLYS029B		
L									
		nanges may be r				inks provided.			
<u>htt</u>	ps://v	www.ti.com/proc	luct/TMAG5	110	<u>-Q1</u>				
Eri	r <mark>or!</mark> B	ookmark not o	lefined.						
Re	ason	for Change:							
То	accur	ately reflect dev	ice characte	erist	ics.				
An	ticipa	ated impact on	Fit, Form,	Fu	nction, Qu	ality or Reliabil	ity (	posit	tive / negative):
the	e actu	al device.							ere are no changes to
Ch	ange	s to product id	entificatio	n re	esulting fro	om this notifica	tion	:	
No	ne.								
Pre	oduct	Affected:							
1		110A2AQDBVRQ1	TMAG511	042	AQDBVRQ1	TMAG5110B2A0		RO1	TMAG5110B2AQDBVRQ1
		110C2AQDBVRQ1			AQDBVRQ1	TMAG511062A0			TMAG5110B2AQDBVRQ1
	VIAG5:	111B2AQDBVRQ1	TMAG511	184	AQDBVRQ1	TMAG5111C2AQDBVRQ1 TMAG5111C4AQDE			TMAG5111C4AQDBVRQ1
		tions regarding es Representativ		e-m	nails can be	sent to the cont	act s	hown	below or your local

Location	E-Mail				
WW PCN Team	PCN ww admin team@list.ti.com				

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